

CapStone™

Reduce Costs 20-30% Over the 5335.



mks | ESI

CapStone provides a laser-based FPC processing solution that utilizes a new generation of laser technology and laser control capabilities to simultaneously deliver high-quality, high-speed via drilling.

The CapStone™ UV-laser drilling system provides leading-edge FPC manufacturers with a high throughput laser-based solution for processing flexible circuit interconnects at higher levels of precision—even on thinner materials. Breakthrough productivity using laser and laser control technology optimized for FPC processing enables flex PCB manufacturers to extend their capabilities and cost-effectively address a wider range of requirements associated with high-volume flex processing at up to and beyond 30% more cost-effectively than the 5335.



Laser control maximizes blind via throughput and yields.

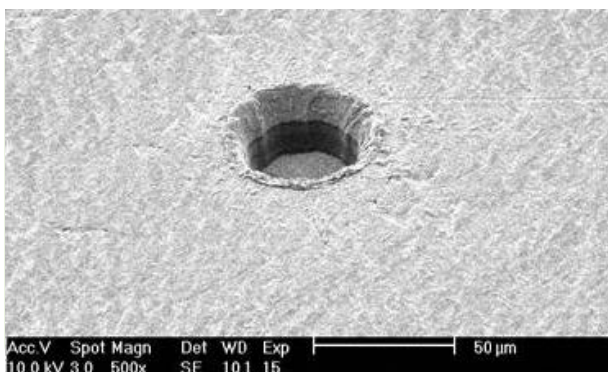
Dramatically increase your blind via processing speeds using ESI's new, patented DynaClean™ feature that turns your multi-pass blind via process into a single pass. Minimize heat effects with up to 10m/s via drilling process velocities using AcceleDrill™ beam positioning technology.

High-performance laser drives efficiency and lowers costs.

Highest UV nsec FPC drilling industry repetition rate with optimized laser characteristics delivers higher throughput and wider process windows. Laser designed and tested in high-volume 24/7 manufacturing environments to extend laser life and reduce maintenance requirements.

Process a wide range of current and next-generation materials.

CapStone applies ESI's decades of laser-material interaction expertise to provide higher performance. This enables FPC manufacturers to drill high-density designs with an increased yield—while limiting incidental damage.



Extend Your Flex Processing Capabilities

- Highest productivity and yields for small blind vias and through vias in thin materials
- High-quality vias down to 25 µm
- Custom optimized laser for wide process window and high productivity